



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



SEI-110-02-GF-S-E-TR



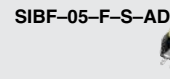
SEI-120-02-GF-S



SIBF-10-F-S-AD



SIBF-25-F-S-AD



SIBF-05-F-S-AD

(1.00 mm) .0394" (SEI) (1.27 mm) .050" (SIBF)

SEI, SIBF SERIES

ONE-PIECE INTERFACE

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEI

Insulator Material: Liquid Crystal Polymer
Contact Material: Phosphor Bronze
Plating: Au over 50 μ" (1.27 μm) Ni
Current Rating: 2.3 A per pin (1 pin powered)
Operating Temp Range: -55 °C to +125 °C
Mating Force: 50 g (0.49 N) per contact
Voltage Rating: 250 VAC
Cycles: 100 min
Contact Deflection: (0.46 mm) .018" nominal
RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004" max (05-25)
 (0.15 mm) .006" max (30)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



SEI	1	NO. OF POSITIONS	02	PLATING OPTION	S	INSERT OPTION	ALIGNMENT OPTION	OTHER OPTION
		05, 10, 15, 20, 25, 30 (Standard sizes)		-G = 10 μ" (0.25 μm) Gold -GF = 3 μ" (0.08 μm) Gold flash		Leave blank for Short Version (No screw down inserts or holes) -E = #2-56 x 1/16" screw thread -M = 2.00 mm x 0.40 mm screw thread	Leave blank for no Alignment Pin -AT = Alignment Pin Top Side -AB = Alignment Pin Bottom Side	-TR = Tape & Reel

SHORT VERSION
 No. of positions x (1.00) .03937 + (0.41) .016
 (6.10) .240 (4.95) .195
 01

INSERT OPTIONS
 (1.65) .065 (0.31) .012
 ((No. of positions-1) x (1.00) .03937) + (7.62) .300
 (3.43) .135
 Threaded Insert (2)

-AT OPTION
 (0.89) .035 DIA (1.27) .050 (4.32) .170

-AB OPTION
 (1.27) .050 (4.32) .170 (0.89) .035 DIA

RUGGEDIZED BY SAMTEC • Threaded insert option

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SIBF

Insulator Material: Black Liquid Crystal Polymer
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50 μ" (1.27 μm) Ni
Current Rating: 2.5 A per pin (1 pin powered)
Operating Temp Range: -55 °C to +125 °C
Voltage Rating: 155 VAC
RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004" max (05-20)
 (0.15 mm) .006" max (25)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



SIBF	NO. OF POSITIONS	PLATING OPTION	S	OPTION
	-05, -10, -20, -25	-F = Flash Gold, Matte Tin on tail		-AD = Top & Bottom Alignment Pin

-AD OPTION
 (6.25) .246 (7.50) .295 (1.27) .050 (0.70) .028 (4.00) .158 (3.00) .118
 No. of positions x (1.27) .050 - (3.81) .150
 (1.00) .040

ALSO AVAILABLE (MOQ Required)

- Additional positions
- Top or bottom side only alignment pin

Contact Samtec.